

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3693484

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YEN-CHUN LIU	12/22/2015
HUI-WEN CHANG	12/22/2015
HSIANG-YEN TSAO	12/22/2015
KUO-CHAN CHIOU	12/22/2015
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14974616
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DATE SIGNED:	01/13/2016
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, Yen-Chun LIU, Hui-Wen CHANG, Hsiang-Yen TSAO and Kuo-Chan CHIOU hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: EPOXY RESIN COMPOSITIONS AND THERMAL INTERFACE MATERIALS COMPRISING THE SAME

Filed: 18-Dec-2015 Serial No. 14/974,616

Executed on: December 22, 2015

WHEREAS, Industrial Technology Research Institute of No. 195, Sec. 4, Chang Hsing Rd., Chung, Hsinchu 31040, Taiwan, R. O. C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Full name of sole or first inventor: Yen-Chun LIU	
Inventor's signature: <u>Yen-Chun LIU</u>	Date: <u>2015/12/22</u>

Full name of second inventor: Hui-Wen CHANG	
Inventor's signature: <u>Hui-Wen CHANG</u>	Date: <u>2015/12/22</u>

Full name of third inventor: Hsiang-Yen TSAO

Inventor's signature:

Hsiang-Yen TSAO

Date:

2015/12/22

Full name of fourth inventor: Kuo-Chan CHIOU

Inventor's signature:

Chiu

Date:

2015/12/22